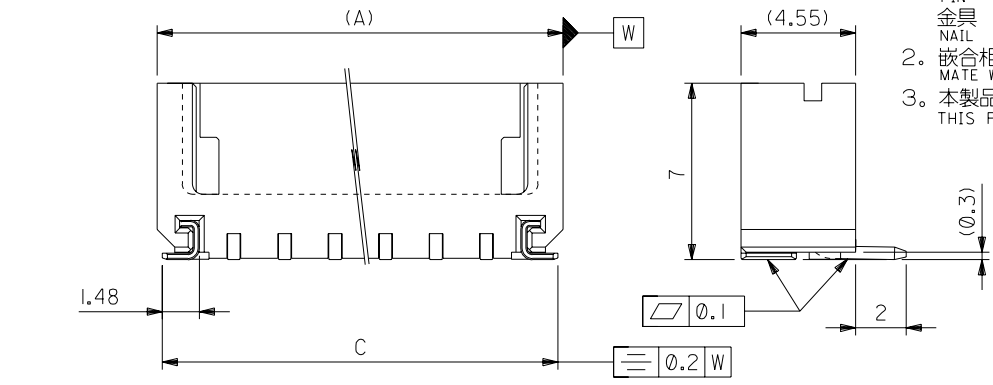
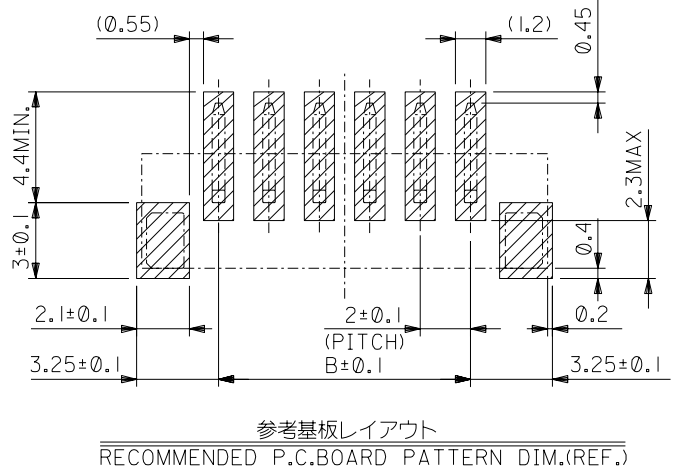
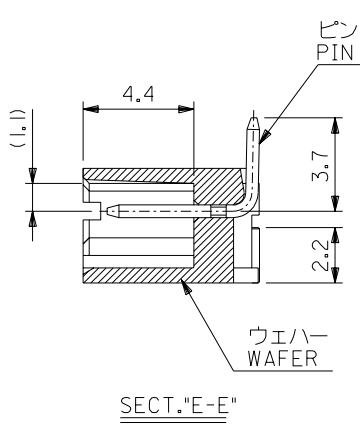
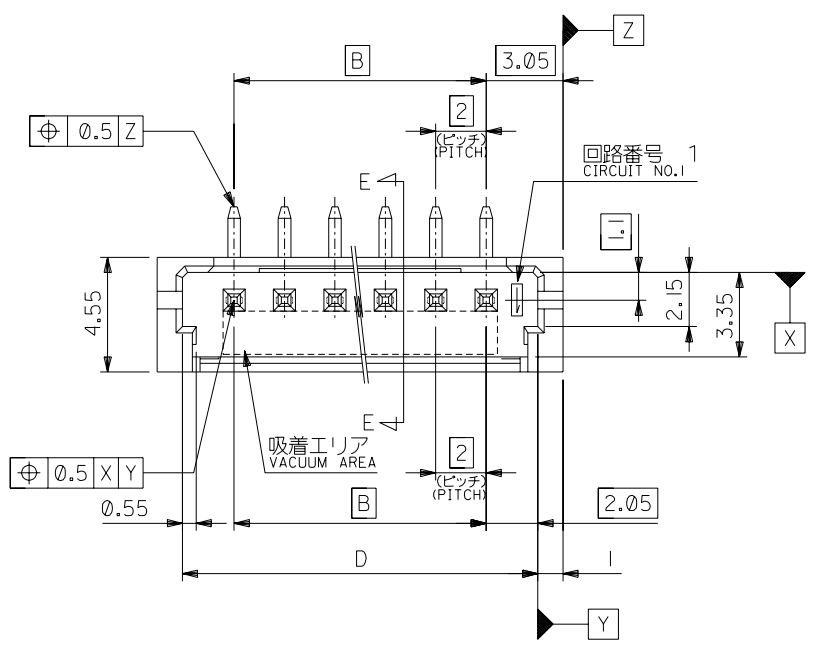


DO NOT SCALE DRAWING

DWG. NO. SD-55460-010

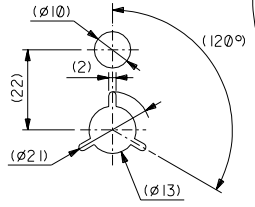
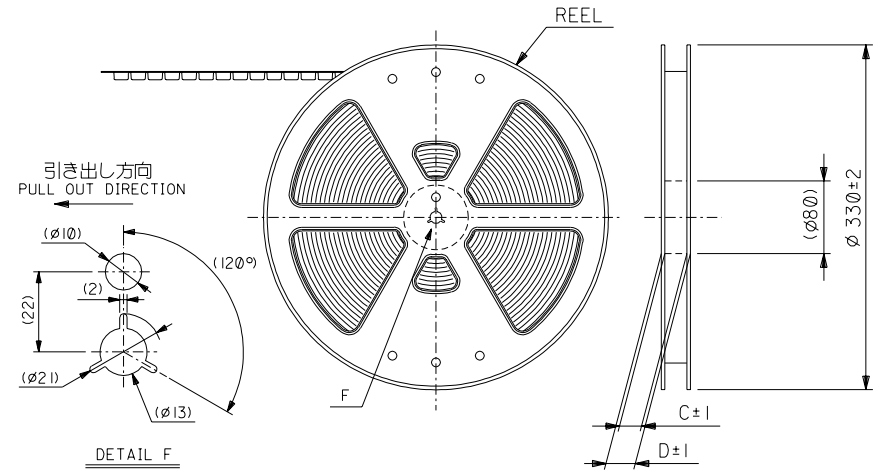


注記  
NOTES

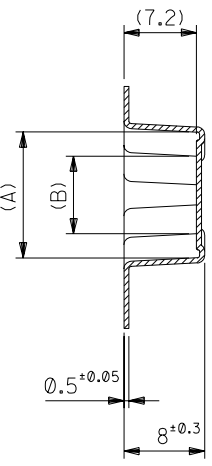
1. 材質 MATERIAL  
 ウェハー: PPA, (UL94V-0)  
 WAFER: PPA, (UL94V-0)  
 ピン: 黄銅 (□0.5), 銅下地錫メッキ  
 PIN: BRASS (□0.5), TIN OVER COPPER PATING  
 金具: リン青銅 (+0.25), ニッケル下地錫メッキ  
 NAIL: PHOSPHOR BRONZE, TIN OVER NICKEL PATING
2. 嵌合相手: 51090, 52484 シリーズ  
 MATE WITH 51090, 52484 SERIES.
3. 本製品は 55460-\*\*\*10 の鉛フリー品である。  
 THIS PRODUCT IS LEAD FREE OF 55460-\*\*\*10.

32.1	33.7	28	34.1	55460-1519	15
28.1	29.7	24	30.1	-1319	13
26.1	27.7	22	28.1	-1219	12
22.1	23.7	18	24.1	-1019	10
18.1	19.7	14	20.1	-0819	8
16.1	17.7	12	18.1	-0719	7
14.1	15.7	10	16.1	-0619	6
12.1	13.7	8	14.1	-0519	5
10.1	11.7	6	12.1	-0419	4
8.1	9.7	4	10.1	-0319	3
6.1	7.7	2	8.1	55460-0219	2
D	C	B	A	MATERIAL NO.	種数 CKTS.

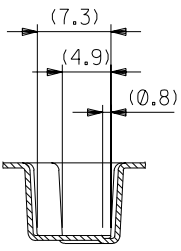
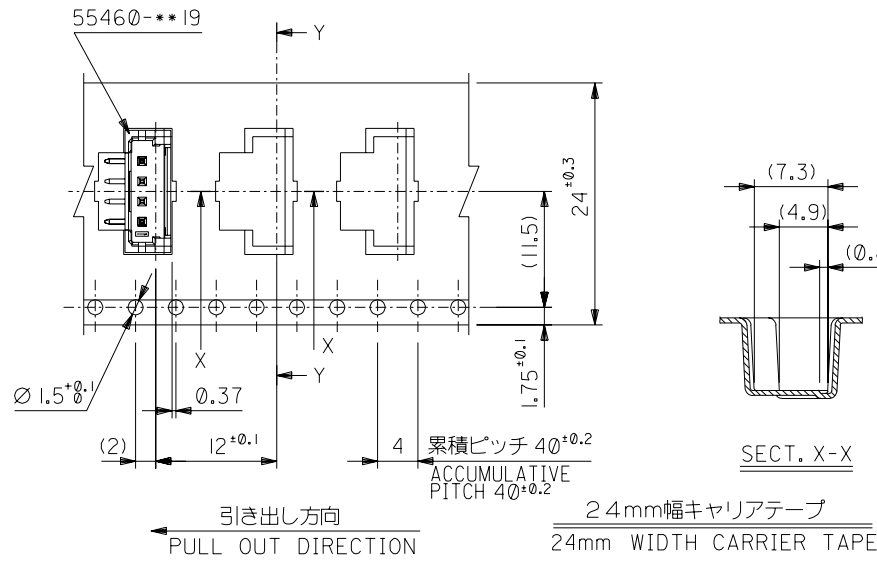
66 NO. DRWN: CH'K: APPR: 63 NO. DRWN: CH'K: APPR: 62 NO. DRWN: CH'K: APPR: 新製作成 04/05/13 RELEASED 26 INO. J2004-4205 DRWN: T.UENO CH'K: M.SASAO APPR: M.SASAO 新製作成 04/03/29 RELEASED 26 INO. J2004-3410 DRWN: T.UENO CH'K: M.SASAO APPR: M.SASAO	MATERIAL 材料 注記参照 SEE NOTES FINISH 仕上げ 注記参照 SEE NOTES WIRE RANGE 適用層被範囲 // INS. RANGE 被覆外径 //	GENERAL TOLERANCES: (UNLESS SPECIFIED) 一般公差 10 UNDER 未満 ±0.2 10 OVER 30 UNDER 未満 ±0.25 30 OVER 以上 ±0.3 ANGLE 角度 ±3°	SCALE 1:1 DESIGN UNITS 25.4mm INCH DRAWN BY & DATE T.UENO '04/03/29 CHECKED BY & DATE M.SASAO '04/03/29 APPROVED BY & DATE M.SASAO '04/03/29 CAD FILENAME SD-55460-010.S01	MODEL NO. 55460-***19 DIMENSIONS: 25.4mm INCH SHT 2 REV 1 TITLE: 2.0 W-T-B CONN WAFER ASSY FOR SMT ST -LEAD FREE- MOLEX MOLEX INCORPORATED MATERIAL NO. SEE CHART DRAWING NO. SD-55460-010 SHEET NO. 1	
					55460-***19
					DIMENSIONS: 25.4mm INCH
					SHT 2 REV 1



DETAIL F



SECT. Y-Y



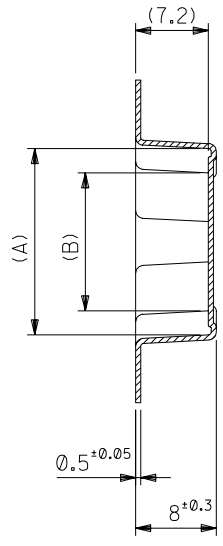
SECT. X-X

NOTES

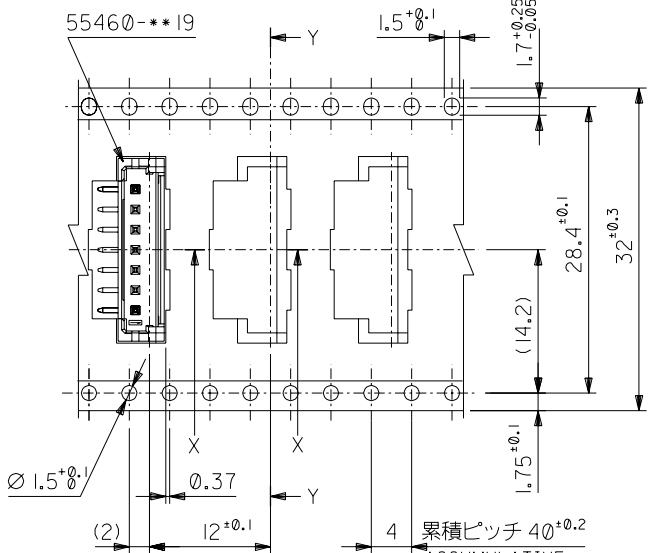
- 梱包数量：900個/リール  
NUMBER OF CONNECTOR:900PCS/REEL
- リードテープ長さ  
LEAD TAPE LENGTH
- トップテープの剥離強度：0.1N～1.3N(10gf～130gf) (剥離方向は下図参照)  
PEELING OFF FORCE OF TOP TAPE: 0.1N～1.3N(10gf～130gf) (PEELING DIRECTION IS SHOWN IN FOLLOWING FIG.)  
 <剥離速度：300mm/min (参考)>  
 PEELING SPEED:300mm/min. (REFERENCE)
- 55460-\*\*-19の詳細寸法については図面SD-55460-010を参照下さい。  
RE DETAILED DIMENSIONS,SEE SD-55460-010
- 材料 (MATERIAL)  
キャリアテープ(CARRIER TAPE):ポリプロピレン(POLYPROPYLENE)  
トップテープ (TOP TAPE): PET ,PE ,PEF  
リール (REEL) : ポリスチレン (PS) <リサイクル材を含む>  
POLYSTYRENE(PS)<RECYCLE MATERIAL CONTAINED>
- 本製品は 55460-\*\*-90 の鉛フリー品である。  
THIS PRODUCT IS LEAD FREE OF 55460-\*\*-90.

24	29.4	25.4	11.7	16.45	55460-0672	6	
			9.7	14.45	55460-0572	5	
			7.7	12.45	55460-0472	4	
			5.7	10.45	55460-0372	3	
			3.7	8.45	55460-0272	2	
キャリアテープ幅		D	C	B	A	MATERIAL NO.	種数 CKTS.

EC NO. DRWN: CH'K: APPR:		EC NO. DRWN: CH'K: APPR:		EC NO. DRWN: CH'K: APPR:		EC NO. DRWN: CH'K: APPR:		EC NO. DRWN: CH'K: APPR:		新規作成 RELEASED EC NO. J2004-3410 DRWN: T.UENO '04/03/29 CH'K: M.SASAO '04/03/29 APPR: M.SASAO '04/03/29		MATERIAL 材料	注記参照 SEE NOTES		GENERAL TOLERANCES: (UNLESS SPECIFIED) 一般公差		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION		DIMENSIONS: SHT REV	
										DESCRIPTION		FINISH 仕上げ	//		10 UNDER 未満 ±0.2		DRAWN BY & DATE T.UENO '04/03/29		TITLE: 2.0 W+B Conn WAFER Assy Embstp pkg -LEAD FREE-			
										WIRE RANGE 適用電線範囲			//		10 OVER 30 UNDER 未満 ±0.25		CHECKED BY & DATE M.SASAO '04/03/29		MATERIAL NO. DRAWING NO. SHEET NO.			
										INS. RANGE 被覆外径			//		30 OVER 以上 ±0.3		APPROVED BY & DATE M.SASAO '04/03/29		SD-55460-011,S01 SEE CHART SD-55460-011			
										REV				ANGLE 角度 ±3°		CAD FILENAME		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.		SIZE B		

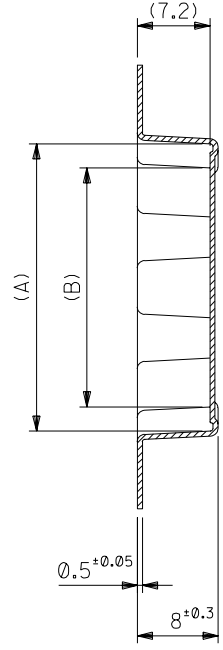


SECT. Y-Y

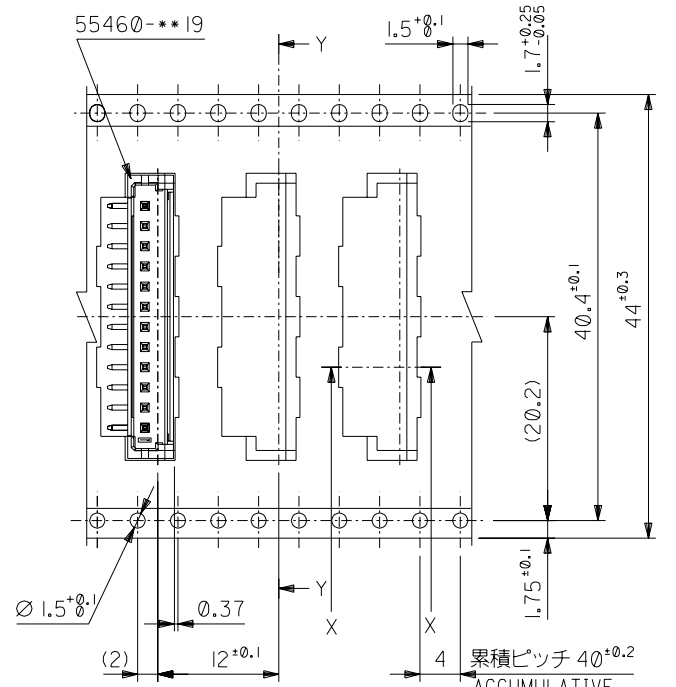


引き出し方向  
PULL OUT DIRECTION

32mm幅キャリアテープ  
32mm WIDTH CARRIER TAPE

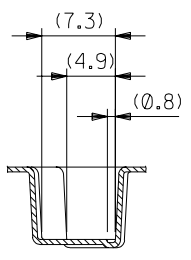


SECT. Y-Y



引き出し方向  
PULL OUT DIRECTION

44mm幅キャリアテープ  
44mm WIDTH CARRIER TAPE



SECT. X-X

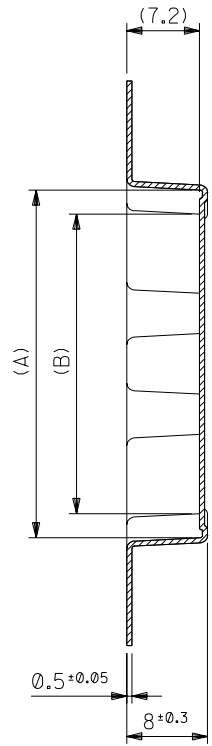
44	49.4	45.4	25.7	30.45	55460-1372	13
			23.7	28.45	55460-1272	12
32	37.4	33.4	19.7	24.45	55460-1072	10
			15.7	20.45	55460-0872	8
			13.7	18.45	55460-0772	7
キャリアテープ幅	D	C	B	A	MATERIAL NO.	種数 CKTS.

DO NOT SCALE DRAWING

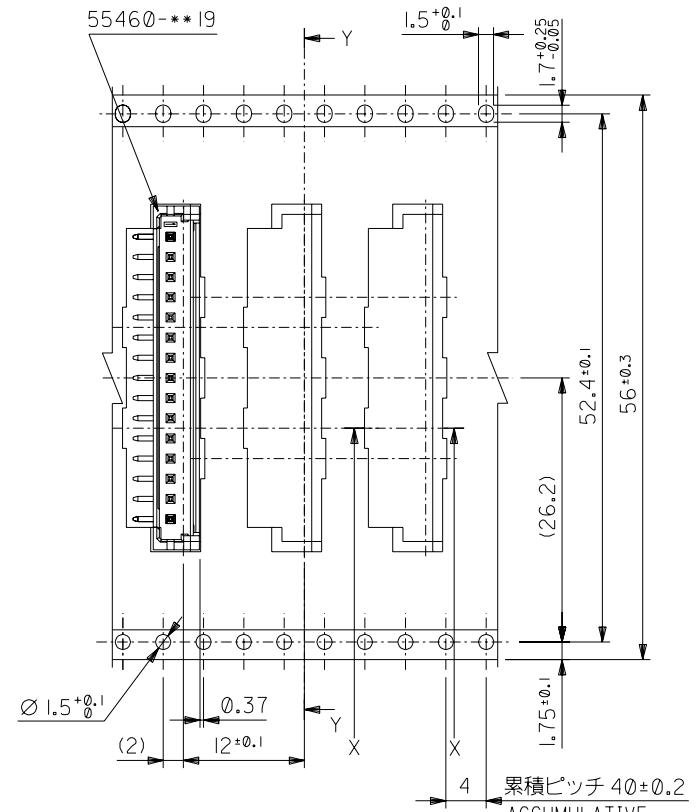
EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:
					SEE SHEET 1 OF 3

DESCRIPTION	MATERIAL 材料	GENERAL TOLERANCES: (UNLESS SPECIFIED) 一般公差
FINISH 仕上げ	SHEET 1 OF 3参照 SEE SHEET 1 OF 3	10 UNDER 未滿 ±0.2
WIRE RANGE 適用電線範囲	//	10 OVER 30 UNDER 未滿 ±0.25
INS. RANGE 被覆外径	//	30 OVER 以上 ±0.3
REV		ANGLE 角度 ±3°

SCALE	DESIGN UNITS <input checked="" type="checkbox"/> mm <input type="checkbox"/> INCH	THIRD ANGLE PROJECTION	DIMENSIONS: <input type="checkbox"/> mm <input type="checkbox"/> INCH <input checked="" type="checkbox"/> mm ONLY	SHT	REV
DRAWN BY & DATE T.UENO '04/03/29	TITLE: 2.0 WtB Conn WAFER Assy Embstp pkg -LEAD FREE-				
CHECKED BY & DATE M.SASAO '04/03/29	MOLEX INCORPORATED				
APPROVED BY & DATE M.SASAO '04/03/29	MATERIAL NO. SD-55460-011.S02	DRAWING NO. SEE CHART	SHEET NO. SD-55460-011	2 OF 3	
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.					SIZE B

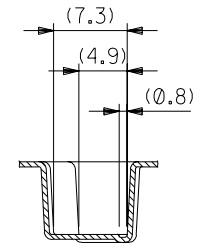


SECT. Y-Y



引き出し方向  
PULL OUT DIRECTION

56mm幅キャリアテープ  
56mm WIDTH CARRIER TAPE



SECT. X-X

56	61.4	57.4	29.7	34.45	55460-1572	15
キャリアテープ幅	D	C	B	A	MATERIAL NO.	種数 CKTS.

55460-***72		MODEL NO.	DIMENSIONS:		SHT	REV
SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	<input type="checkbox"/> mm	<input type="checkbox"/> INCH	<input checked="" type="checkbox"/> mm	REVISION ON CAD ONLY

EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:
EC NO. SEE SHEET 1 OF 3					
DESCRIPTION					
MATERIAL 材料					
FINISH 仕上げ					
WIRE RANGE 適用電線範囲					
INS. RANGE 被覆外径					

SHEET 1 OF 3 参照 SEE SHEET 1 OF 3	
10 UNDER 未満	±0.2
10 OVER 以上 30 UNDER 未満	±0.25
30 OVER 以上	±0.3
ANGLE 角度	±3°

GENERAL TOLERANCES: (UNLESS SPECIFIED) 一般公差	
DRAWN BY & DATE T.UENO '04/03/29	
CHECKED BY & DATE M.SASAO '04/03/29	
APPROVED BY & DATE M.SASAO '04/03/29	
CAD FILENAME SD-55460-011.S03	

TITLE: 2.0 WtB Conn WAFER Assy Embstp pkg -LEAD FREE-			
MOLEX INCORPORATED			
CAD FILENAME SD-55460-011.S03	MATERIAL NO. SEE CHART	DRAWING NO. SD-55460-011	SHEET NO. 3 OF 3
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.			SIZE B